

# DSC2P01

## Silicon NPN epitaxial planar type

For low frequency amplification  
Darlington connection

### ■ Features

- High forward current transfer ratio  $h_{FE}$  with excellent linearity
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

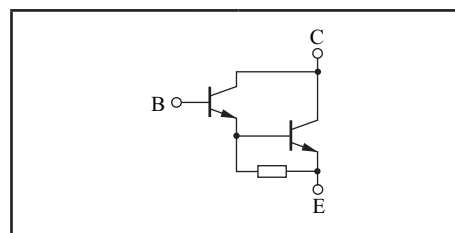
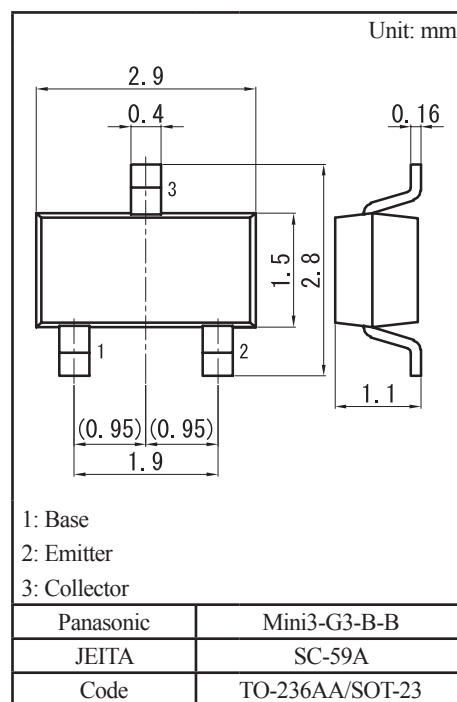
### ■ Marking Symbol: E5

### ■ Packaging

DSC2P01×0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                             | Symbol    | Rating      | Unit             |
|---------------------------------------|-----------|-------------|------------------|
| Collector-base voltage (Emitter open) | $V_{CBO}$ | 60          | V                |
| Collector-emitter voltage (Base open) | $V_{CEO}$ | 50          | V                |
| Emitter-base voltage (Collector open) | $V_{EBO}$ | 5           | V                |
| Collector current                     | $I_C$     | 500         | mA               |
| Peak collector current                | $I_{CP}$  | 750         | mA               |
| Total power dissipation               | $P_T$     | 200         | mW               |
| Junction temperature                  | $T_j$     | 150         | $^\circ\text{C}$ |
| Operating ambient temperature         | $T_{opr}$ | -40 to +85  | $^\circ\text{C}$ |
| Storage temperature                   | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |



### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

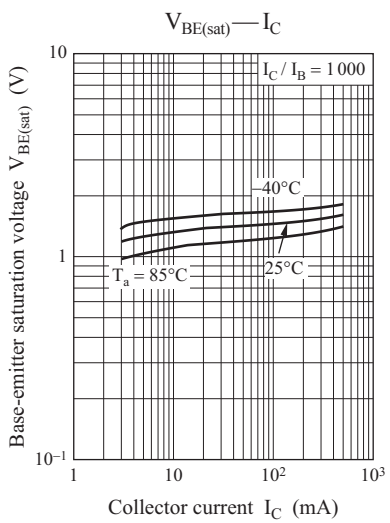
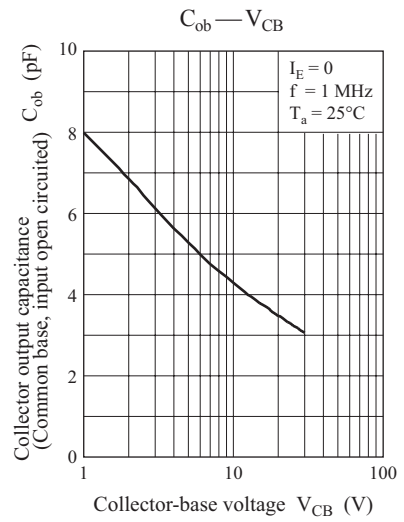
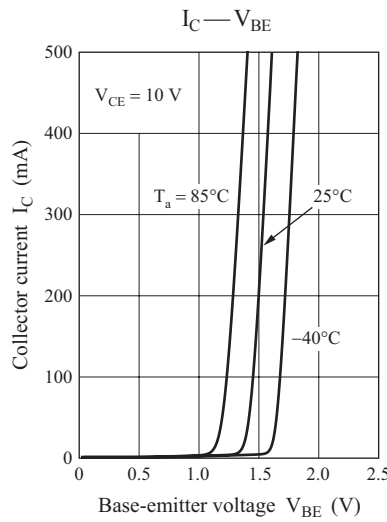
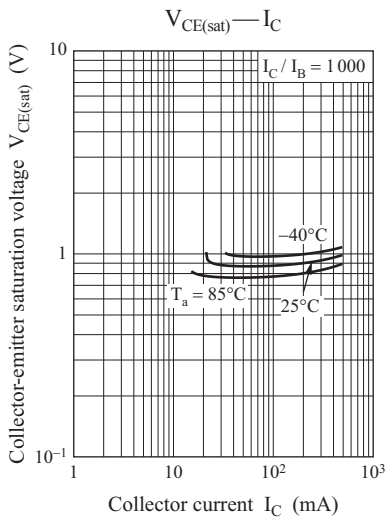
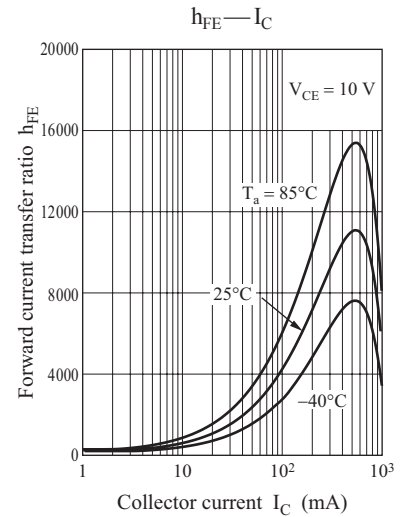
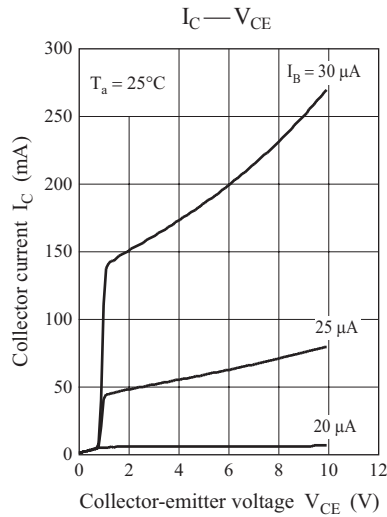
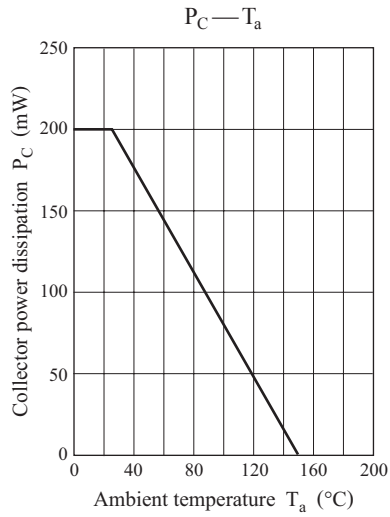
| Parameter                                    | Symbol        | Conditions                                    | Min  | Typ | Max   | Unit |
|--|---------------|---|------|-----|-------|------|
| Collector-base voltage (Emitter open)        | $V_{CBO}$     | $I_C = 100 \mu\text{A}, I_E = 0$              | 60   |     |       | V    |
| Collector-emitter voltage (Base open)        | $V_{CEO}$     | $I_C = 1 \text{ mA}, I_B = 0$                 | 50   |     |       | V    |
| Emitter-base voltage (Collector open)        | $V_{EBO}$     | $I_E = 100 \mu\text{A}, I_C = 0$              | 5    |     |       | V    |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$     | $V_{CB} = 25 \text{ V}, I_E = 0$              |      |     | 100   | nA   |
| Emitter-base cutoff current (Collector open) | $I_{EBO}$     | $V_{EB} = 4 \text{ V}, I_C = 0$               |      |     | 100   | nA   |
| Forward current transfer ratio *1, 2         | $h_{FE}$      | $V_{CE} = 10 \text{ V}, I_C = 500 \text{ mA}$ | 4000 |     | 20000 | —    |
| Collector-emitter saturation voltage *1      | $V_{CE(sat)}$ | $I_C = 500 \text{ mA}, I_B = 0.5 \text{ mA}$  |      |     | 2.5   | V    |
| Base-emitter saturation voltage *1           | $V_{BE(sat)}$ | $I_C = 500 \text{ mA}, I_B = 0.5 \text{ mA}$  |      |     | 3.0   | V    |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*1: Pulse measurement

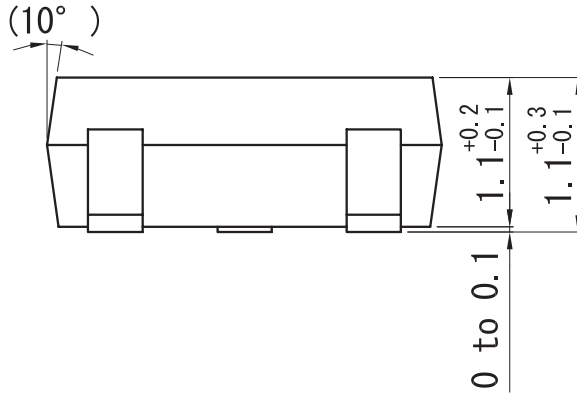
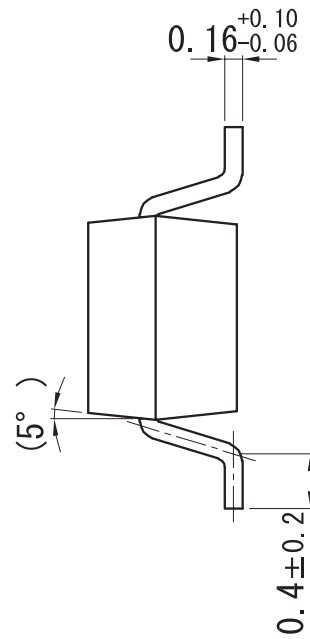
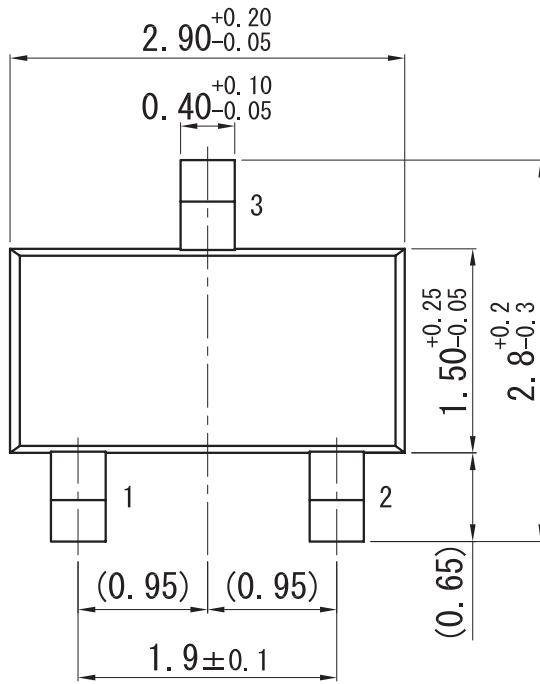
\*2: Rank classification

| Code           | Q             | R             |
|----------------|---------------|---------------|
| Rank           | Q             | R             |
| $h_{FE}$       | 4000 to 10000 | 8000 to 20000 |
| Marking Symbol | E5Q           | E5R           |

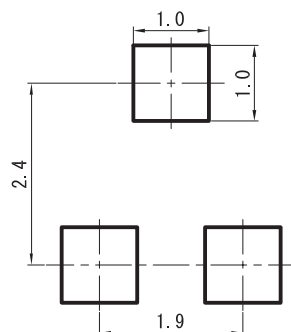


Mini3-G3-B-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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